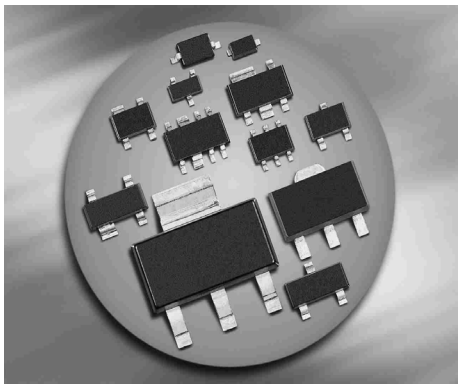
Silicon N_Channel MOSFET Tetrode



- Short-channel transistor with high S / C quality factor
- For low-noise, gain-controlled input stage up to 1 GHz
- Pb-free (RoHS compliant) package

RoHS

ESD (**E**lectro**s**tatic **d**ischarge) sensitive device, observe handling precaution!

Type	Package	Pin Configuration						Marking
BF998	SOT143	1=S	2=D	3=G2	4=G1	-	-	MOs
BF998R	SOT143R	1=D	2=S	3=G1	4=G2	-	-	MRs

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	12	V
Continuous drain current	I_D	30	mA
Gate 1/ gate 2-source current	$\pm I_{G1/2SM}$	10	
Total power dissipation $T_S \leq 76$ °C, BF998, BF998R	P_{tot}	200	
Storage temperature	T_{Stg}	-55 ... 150	°C
Channel temperature	T_{ch}	150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Channel - soldering point[1)], BF998, BF998R	R_{thchs}	≤ 370	K/W

[1]For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

Electrical Characteristics at T_A = 25°C, unless otherwise specified

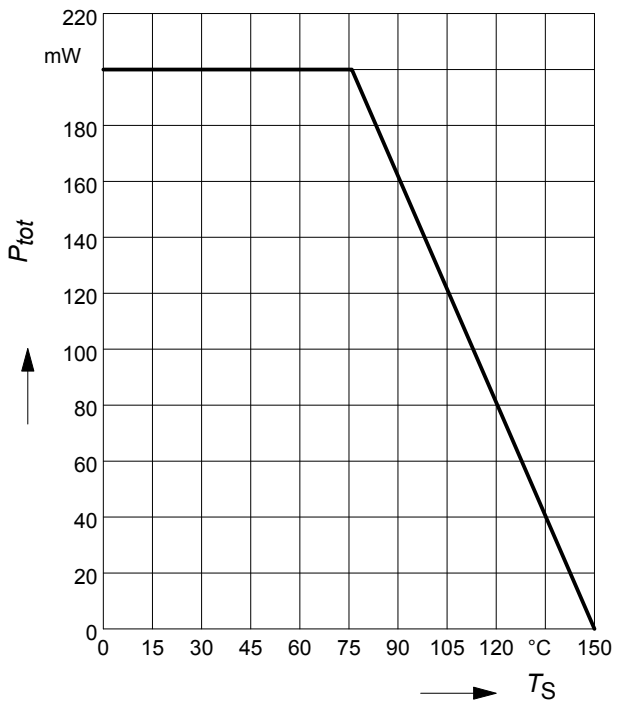
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Drain-source breakdown voltage I_D = 10 µA, V_{G1S} = -4 V, V_{G2S} = -4 V	$V_{(BR)DS}$	12	-	-	V
Gate 1 source breakdown voltage $\pm I_{G2S}$ = 10 mA, V_{G2S} = V_{DS} = 0	$\pm V_{(BR)G1SS}$	8	-	12	
Gate2 source breakdown voltage $\pm I_{G2S}$ = 10 mA, V_{G2S} = V_{DS} = 0	$\pm V_{(BR)G2SS}$	8	-	12	
Gate 1 source leakage current $\pm V_{G1S}$ = 5 V, V_{G2S} = V_{DS} = 0	$\pm I_{G1SS}$	-	-	50	nA
Gate 2 source leakage current $\pm V_{G2S}$ = 5 V, V_{G2S} = V_{DS} = 0	$\pm I_{G2SS}$	-	-	50	nA
Drain current V_{DS} = 8 V, V_{G1S} = 0 , V_{G2S} = 4 V	I_{DSS}	5	9	15	mA
Gate 1 source pinch-off voltage V_{DS} = 8 V, V_{G2S} = 4 V, I_D = 20 µA	$-V_{G1S(p)}$	-	0.8	2.5	V
Gate 2 source pinch-off voltage V_{DS} = 8 V, V_{G1S} = 0 , I_D = 20 µA	$-V_{G2S(p)}$	-	0.8	2	

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Forward transconductance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V	g_{fs}	20	24	-	-
Gate1 input capacitance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 10 MHz	C_{g1ss}	-	2.1	2.5	pF
Gate 2 input capacitance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 10 MHz	C_{g2ss}	-	1.2	-	pF
Feedback capacitance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 10 MHz	C_{dg1}	-	25	-	fF
Output capacitance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 10 MHz	C_{dss}	-	1.1	-	pF
Power gain V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 45 MHz V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 800 MHz	G_p	 - -	 28 20	 - -	dB
Noise figure V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 45 MHz V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 800 MHz	F	 - -	 2.8 1.8	 - -	dB
Gain control range V_{DS} = 8 V, V_{G2S} = 4 ...-2 V, f = 800 MHz	ΔG_p	40	50	-	

Total power dissipation $P_{tot} = f(T_S)$

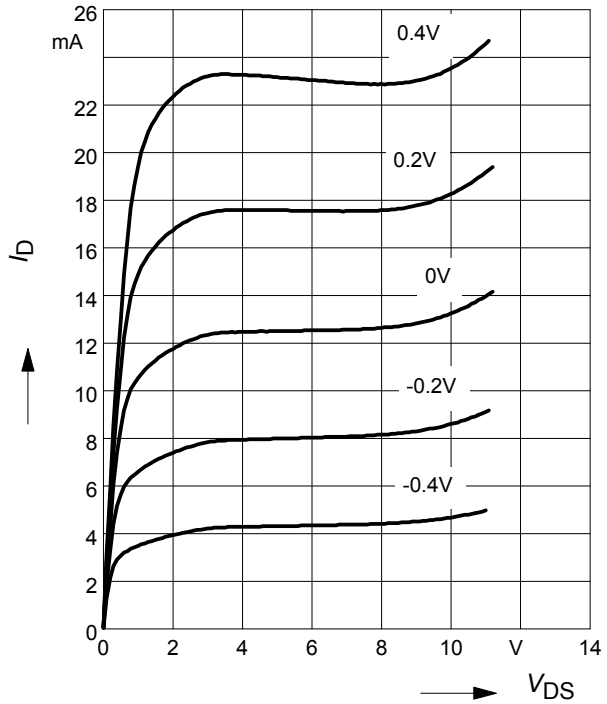
BF998, BF998R



Output characteristics $I_D = f(V_{DS})$

V_{G2S} = 4 V

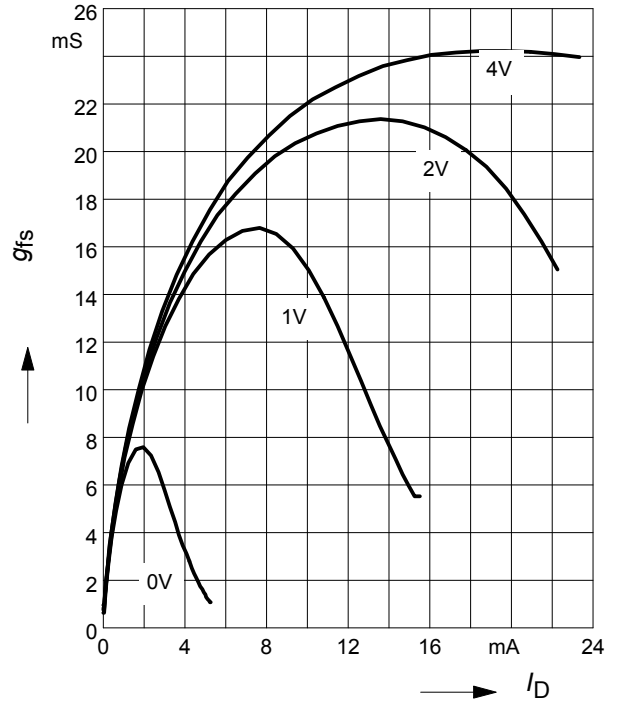
V_{G1S} = Parameter



Gate 1 forward transconductance

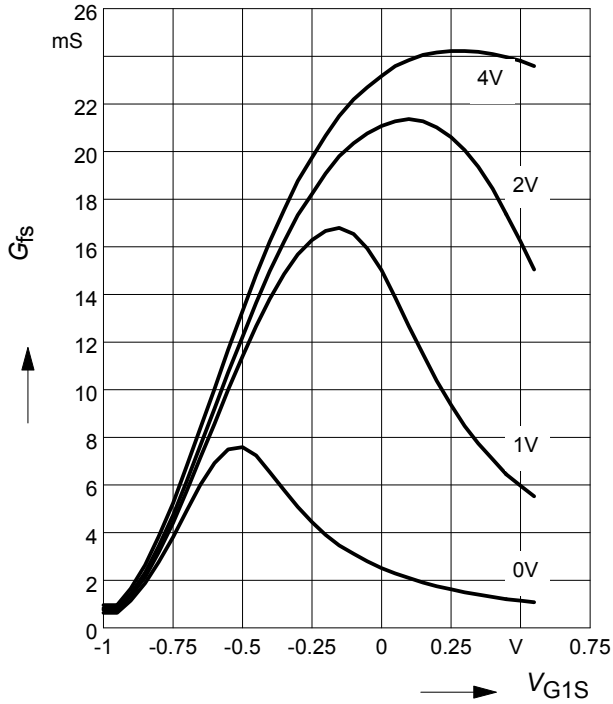
$g_{fs} = f(I_D)$

V_{DS} = 5V, V_{G2S} = Parameter



Gate 1 forward transconductance

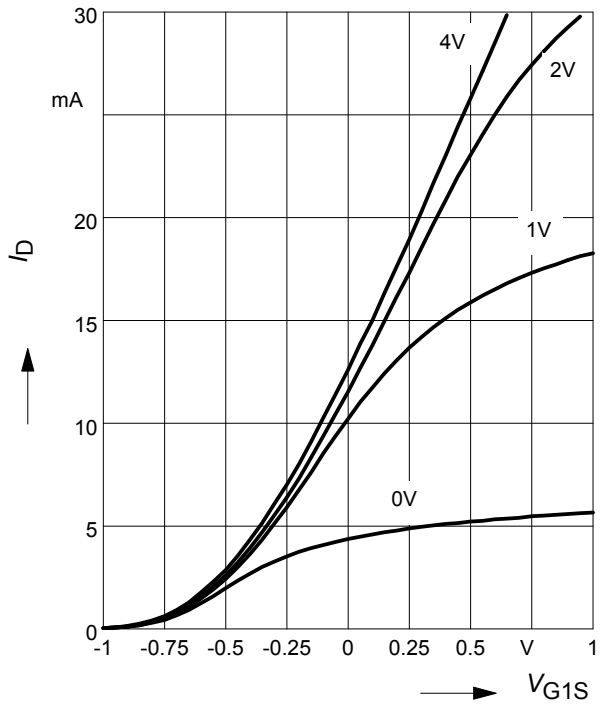
$g_{fs1} = f(V_{G1S})$



Drain current $I_D = f(V_{G1S})$

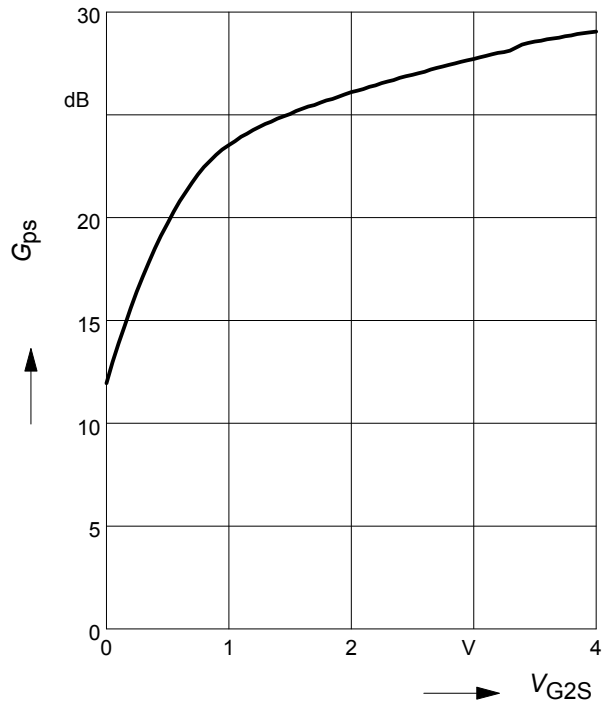
V_{DS} = 5V

V_{G2S} = Parameter



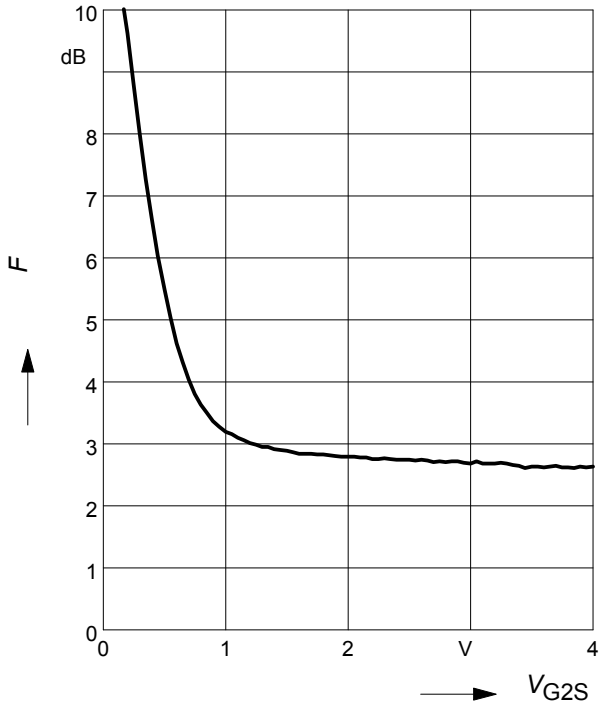
Power gain $G_{ps} = f\ (V_{G2S})$

f = 45 MHz



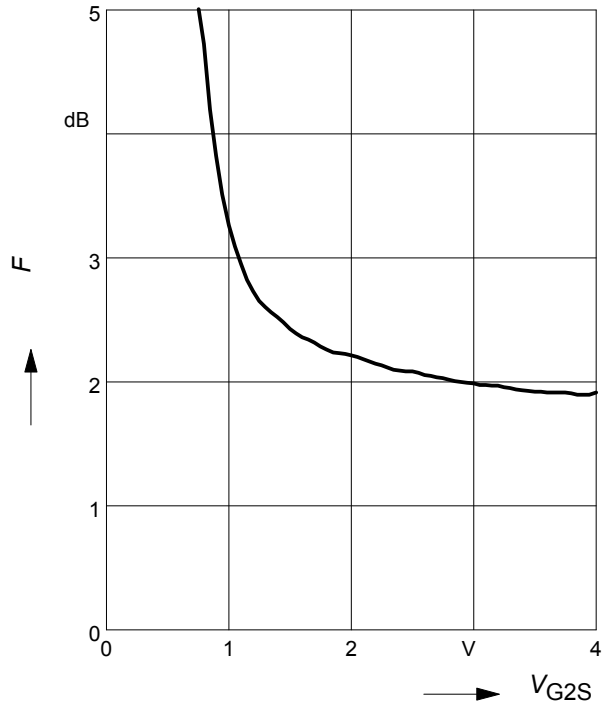
Noise figure $F = f\ (V_{G2S})$

f = 45 MHz

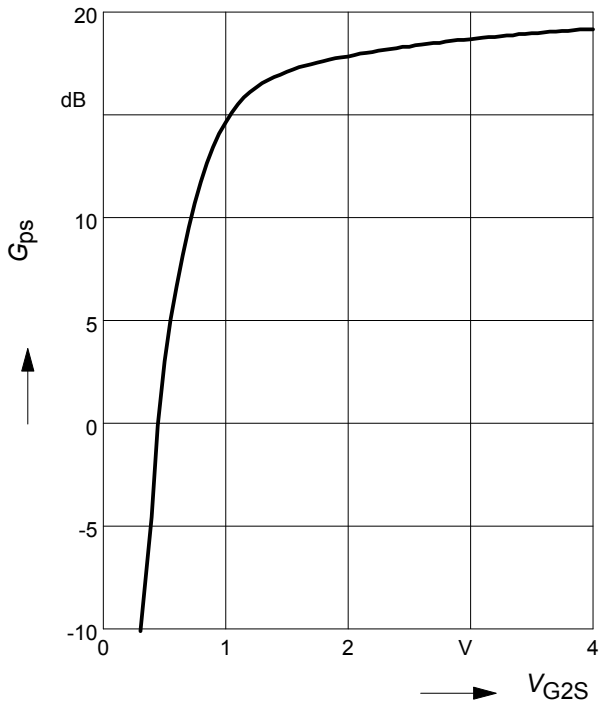


Noise figure $F = f\ (V_{G2S})$

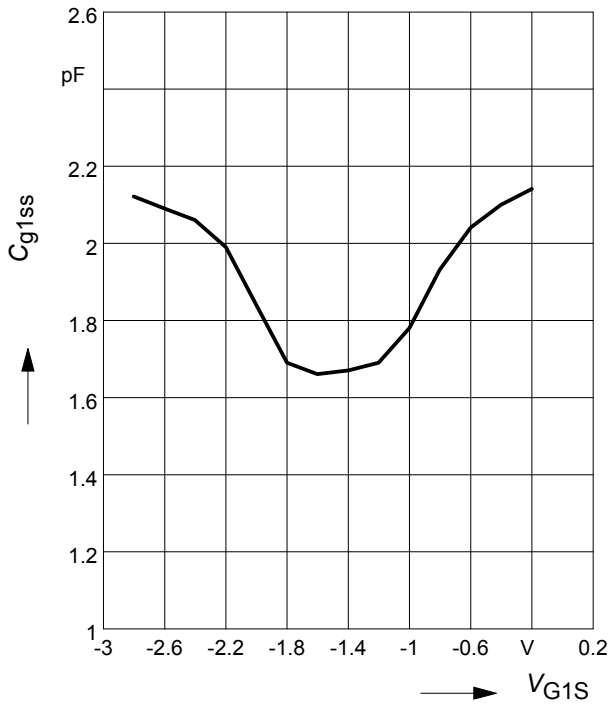
f = 800 MHz



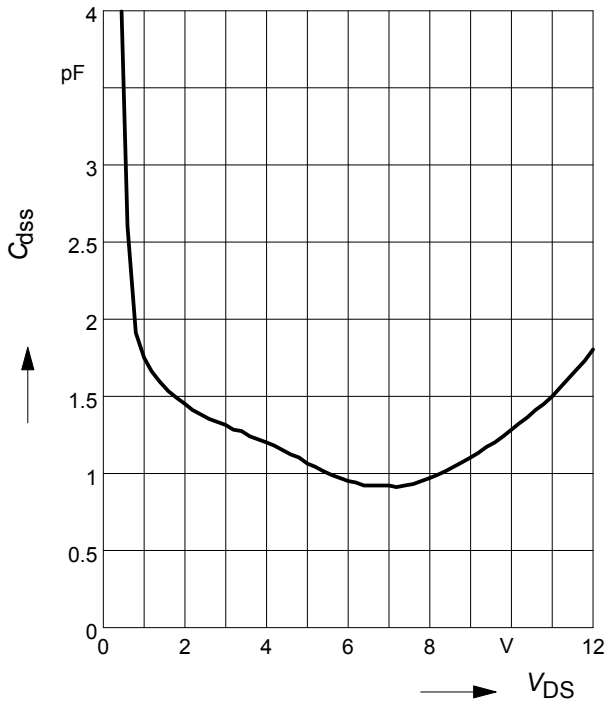
Power gain $G_{ps} = f\ (V_{G2S})$
f = 800 MHz



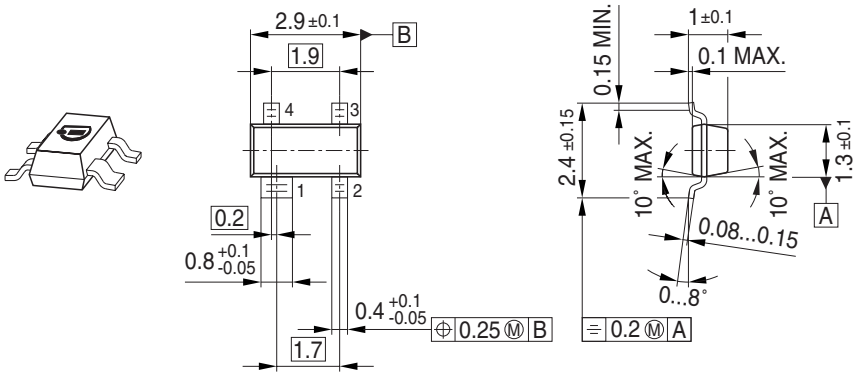
Gate 1 input capacitance $C_{g1ss} = f\ (V_{G1S})$



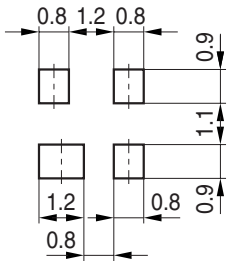
Output capacitance $C_{dss} = f(V_{DS})$



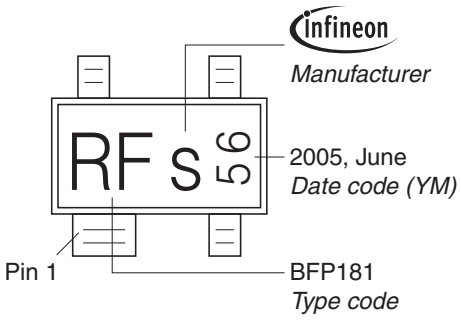
Package Outline



Foot Print

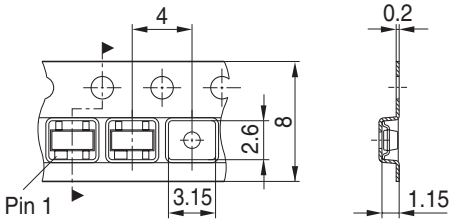


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



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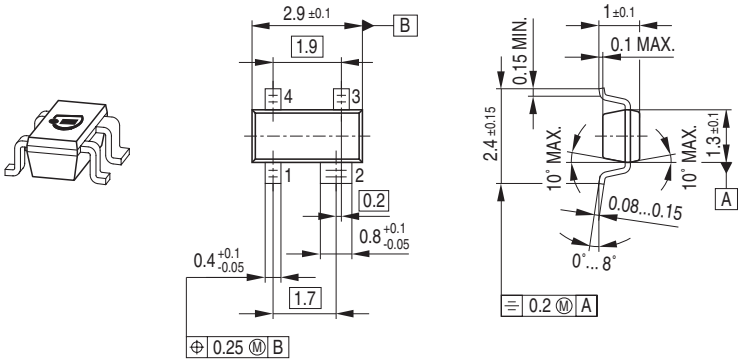

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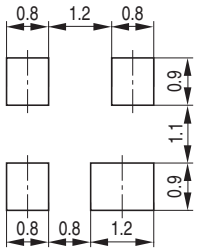

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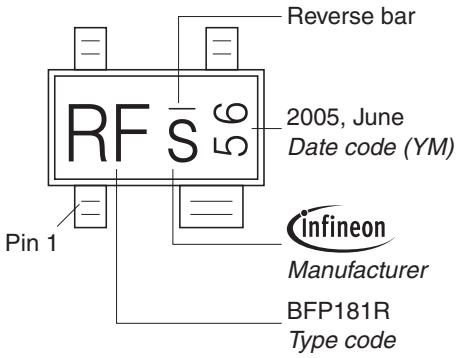

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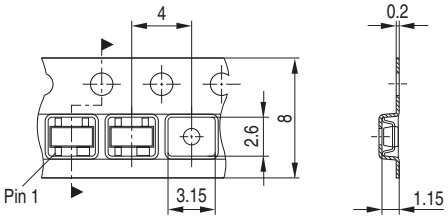

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